AUTOMOTIVE GRADE

RoHS³

HALOGEN

FREE

GREEN

(5-2008)



Solid Tantalum Surface Mount Capacitors TANTAMOUNT™ Molded Case, HI-TMP® High Temperature 150 °C, Automotive Grade



LINKS TO ADDITIONAL RESOURCES













PERFORMANCE / ELECTRICAL CHARACTERISTICS

www.vishav.com/doc?40215

Operating Temperature: -55 °C to +150 °C Capacitance Range: $0.33~\mu F$ to $220~\mu F$ Capacitance Tolerance: $\pm~10~\%, \pm~20~\%$ Voltage Rating: $6.3~V_{DC}$ to $50~V_{DC}$

Note

 For recommended voltage derating guidelines see "Typical Performance Characteristics"

FEATURES

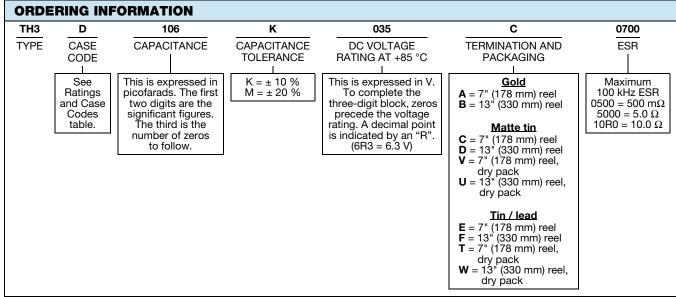
- Operating temperature up to 150 °C with 50 % voltage derating
- AEC-Q200 qualified
- 100 % surge current tested (B, C, D, E case sizes)
- RoHS-compliant terminations available: matte tin (all cases), gold (A, C, D, and E cases)
- Standard EIA 535BAAC case size (A through E)
- · Compliant terminations
- Moisture sensitivity level 1
- Material categorization: for definitions of compliance please see <u>www.vishav.com/doc?99912</u>

Note

* This datasheet provides information about parts that are RoHS-compliant and / or parts that are non RoHS-compliant. For example, parts with lead (Pb) terminations are not RoHS-compliant. Please see the information / tables in this datasheet for details

APPLICATIONS

- Automotive
- Industrial
- High temperature sensors



Notes

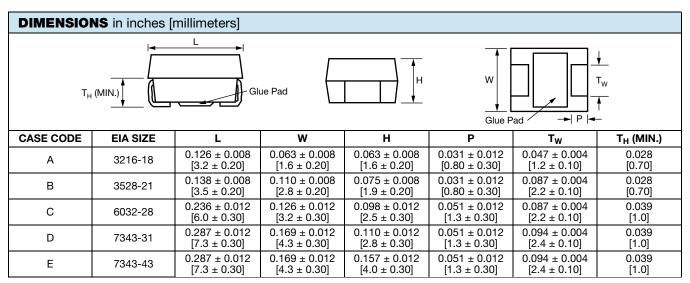
- We reserve the right to supply higher voltage ratings and tighter capacitance tolerance capacitors in the same case size. Voltage substitutions will be marked with the higher voltage rating
- Dry pack as specified in J-STD-033

Revision: 17-Oct-2022

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Note

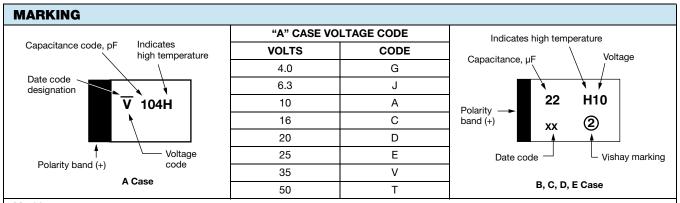
Glue pad (non-conductive, part of molded case) is dedicated for glue attachment (as user option)

RATINGS	AND CASE C	ODES					
μF	6.3 V	10 V	16 V	20 V	25 V	35 V	50 V
0.33						A (11.0)	
0.47					A (14.0)		
0.68							
1.0			A (6.5)	A (5.9)	A (3.0, 5.2) / B (5.0)	A (6.6) / B (4.4)	C (3.3)
1.5						B (4.2) / C (3.3)	
2.2		A (4.6)	A (4.3)	A (5.9) / B (3.5)	A (5.2) / B (3.0)	B (2.5) / C (2.2)	
3.3			A (3.4) / B (3.0)	B (2.7) / C (3.7)	B (3.0) / C (2.0)	B (2.5, 3.5) / C (1.7)	D (1.7)
4.7		A (2.9) / B (2.7)	A (2.9) / B (2.1)	A (5.0) / B (2.9, 1.9) / C (1.7)	A (5.0) / B (2.8) / C (1.6)	B (3.1) / C (1.3) / D (1.0)	C (1.5) / D (0.9)
6.8		A (2.6)	A (2.6, 2.0) / B (1.8) / C (1.7)		B (2.4) / C (1.4)	C (1.8) / D (0.9)	D (0.9)
10	A (3.4, 2.7)	A (3.4, 2.0) / B (1.8) / C (1.8, 1.7)	B (2.0) / C (1.4, 0.8)	C (1.1)	C (1.1) / D (0.9)	C (1.6) / D (0.25, 0.3, 0.7)	D (0.8) / E (0.5)
15	B (1.8)	A (2.9, 2.0) / B (2.0, 1.8, 1.5) / C (1.8, 1.4)	B (2.0) / C (1.0)	B (2.0) / C (1.0) / D (0.9)	B (1.4, 2.0) / C (1.2) / D (0.7)	D (0.7)	
22	B (2.0, 1.5)	B (1.5) / C (1.5, 1.1)	B (1.9) / C (0.8, 1.0) / D (0.8)	C (1.0) / D (0.7)	D (0.6)	D (0.3, 0.6) / E (0.5)	
33	B (1.9, 1.7)	B (1.9, 1.4) / D (0.8)	C (0.9, 0.6) / D (0.6)	D (0.6)	D (0.5)		
47	B (1.8) / C (0.8)	B (1.8) / C (0.8, 0.5) / D (0.6)	C (0.8, 0.6) / D (0.6)	D (0.7) / E (0.6)	E (0.6)		
68	B (1.8)	C (1.0, 0.8) / D (1.0, 0.6, 0.4)	D (0.6)	E (0.6)			
100	E (0.3)	C (0.9, 0.5) / D (0.6)	D (0.6) / E (0.6, 0.15)				
150		D (0.6)					
220		E (0.5)					<u> </u>

Note

• ESR limits in Ω are shown in parenthesis





Marking

Capacitor marking includes an anode (+) polarity band, capacitance in microfarads and the voltage rating. "A" case capacitors use a letter code for the voltage and EIA capacitance code.

The Vishay identification marking is included if space permits. Vishay marking ("circled 2") may show additives in the form of short lines, depicting actual manufacturing facility. For A case capacitors discontinuation in polarity bar maybe used as actual manufacturing facility designation. Capacitors rated at 6.3 V are marked 6 V. Uppercase letter "H" indicates lead (Pb)-free capacitors; lowercase letter "h" indicates SnPb containing capacitors.

A manufacturing date code is marked on all capacitors. for details see FAQ: www.vishay.com/doc?40110.

Call the factory for further explanation.

CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μΑ)	MAX. DF AT +25 °C (%)	MAX. ESR AT +25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		6.3 V _{DC} AT +85 °C; 4 V _{DC} A	T +125 °C; 3.15 V _I	_{DC} AT +150 °C		
10	Α	TH3A106(1)6R3(3)3400	0.6	6	3.40	0.15
10	Α	TH3A106(1)6R3(3)2700	0.6	6	2.70	0.17
15	В	TH3B156(1)6R3(2)1800	0.9	6	1.80	0.22
22	В	TH3B226(1)6R3(2)2000	1.3	6	2.00	0.21
22	В	TH3B226(1)6R3(2)1500	1.3	6	1.50	0.24
33	В	TH3B336(1)6R3(2)1900	2.0	6	1.90	0.21
33	В	TH3B336(1)6R3(2)1700	2.0	6	1.70	0.22
47	В	TH3B476(1)6R3(2)1800	2.8	8	1.80	0.22
47	С	TH3C476(1)6R3(3)0800	2.8	6	0.80	0.37
68	В	TH3B686(1)6R3(2)1800	4.1	6	1.80	0.22
100	Е	TH3E107(1)6R3(3)0300	6.0	6	0.30	0.74
		10 V _{DC} AT +85 °C; 7 V _{DC}	AT +125 °C; 5 V _{DC}	AT +150 °C		
2.2	Α	TH3A225(1)010(3)4600	0.5	6	4.60	0.13
4.7	Α	TH3A475(1)010(3)2900	0.5	6	2.90	0.16
4.7	В	TH3B475(1)010(2)2700	0.5	6	2.70	0.18
6.8	Α	TH3A685(1)010(3)2600	6.8	6	2.60	0.17
10	Α	TH3A106(1)010(3)3400	1.0	6	3.40	0.15
10	Α	TH3A106(1)010(3)2000	1.0	6	2.00	0.19
10	В	TH3B106(1)010(2)1800	1.0	6	1.80	0.22
10	С	TH3C106(1)010(3)1800	1.0	6	1.80	0.25
10	C	TH3C106(1)010(3)1700	1.0	6	1.70	0.25
15	A	TH3A156(1)010(3)2900	1.0	6	2.90	0.16
15	A	TH3A156(1)010(3)2000	1.0	6	2.00	0.19
15	В	TH3B156(1)010(2)2000	1.0	6	2.00	0.21
15	В	TH3B156(1)010(2)1800	1.0	6	1.80	0.22
15	В	TH3B156(1)010(2)1500	1.0	6	1.50	0.24
15	C	TH3C156(1)010(3)1800	1.0	6	1.80	0.25
15	C	TH3C156(1)010(3)1400	1.0	6	1.40	0.28

- Part number definitions:
 - (1) Capacitance tolerance: K, M
 - (2) Termination and packaging: C, D, E, F, V, U, T, W
 - (3) Termination and packaging: A, B, C, D, E, F, V, U, T, W

STANDARD					MAX. ESR	MAX. RIPPLE
CAPACITANCE (µF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μA)	MAX. DF AT +25 °C (%)	MAX. ESR AT +25 °C 100 kHz (Ω)	100 kHz I _{RMS} (A)
		10 V _{DC} AT +85 °C; 7 V _{DC}	AT +125 °C; 5 V _{DC}	AT +150 °C		
22	В	TH3B226(1)010(2)1500	2.2	6	1.50	0.24
22	С	TH3C226(1)010(3)1500	2.2	6	1.50	0.27
22	C	TH3C226(1)010(3)1100	2.2	6	1.10	0.32
33	В	TH3B336(1)010(2)1900	3.3	6	1.90	0.21
33	В	TH3B336(1)010(2)1400	3.3	6	1.40	0.25
33	D	TH3D336(1)010(3)0800	3.3	6	0.80	0.43
47	В	TH3B476(1)010(2)1800	4.7	6	1.80	0.22
47	C	TH3C476(1)010(3)0800	4.7	6	0.80	0.37
47	C	TH3C476(1)010(3)0500	4.7	6	0.50	0.47
47	D	TH3D476(1)010(3)0600	4.7	6	0.60	0.50
68	C	(, (,	6.8	8	1.00	0.33
68	C	TH3C686(1)010(3)1000	6.8	8	0.80	0.37
		TH3C686(1)010(3)0800				
68	D	TH3D686(1)010(3)1000	6.8	6	1.00	0.39
68	D	TH3D686(1)010(3)0600	6.8	6	0.60	0.50
68	D	TH3D686(1)010(3)0400	6.8	6	0.40	0.61
100	С	TH3C107(1)010(3)0900	10.0	6	0.90	0.35
100	С	TH3C107(1)010(3)0500	10.0	6	0.50	0.47
100	D	TH3D107(1)010(3)0600	10.0	8	0.60	0.50
150	D	TH3D157(1)010(3)0600	15.0	8	0.60	0.50
220	E	TH3E227(1)010(3)0500	22.0	8	0.50	0.61
		16 V _{DC} AT +85 °C; 10 V _{DC}				
1.0	Α	TH3A105(1)016(3)6500	0.5	4	6.50	0.11
2.2	Α	TH3A225(1)016(3)4300	0.5	6	4.30	0.13
3.3	Α	TH3A335(1)016(3)3400	0.5	6	3.40	0.15
3.3	В	TH3B335(1)016(2)3000	0.5	6	3.00	0.17
4.7	Α	TH3A475(1)016(3)2900	0.8	6	2.90	0.16
4.7	В	TH3B475(1)016(2)2100	0.8	6	2.10	0.2
6.8	Α	TH3A685(1)016(3)2600	1.1	6	2.60	0.17
6.8	Α	TH3A685(1)016(3)2000	1.1	6	2.00	0.19
6.8	В	TH3B685(1)016(2)1800	1.1	6	1.80	0.22
6.8	С	TH3C685(1)016(3)1700	1.1	6	1.70	0.25
10	В	TH3B106(1)016(2)2000	1.6	6	2.00	0.21
10	С	TH3C106(1)016(3)1400	1.6	6	1.40	0.28
10	C	TH3C106(1)016(3)0800	1.6	6	0.80	0.37
15	В	TH3B156(1)016(2)2000	2.4	6	2.00	0.21
15	C	TH3C156(1)016(3)1000	2.4	6	1.00	0.33
22	В	TH3B226(1)016(2)1900	3.5	6	1.90	0.21
22	C	TH3C226(1)016(3)1000	3.5	6	1.00	0.33
22	C	TH3C226(1)016(3)0800	3.5	4.5	0.80	0.37
22	D	TH3D226(1)016(3)0800	3.5	6	0.80	0.43
33	C	TH3C336(1)016(3)0900	5.3		0.90	
				6		0.35
33	C	TH3C336(1)016(3)0600	5.3	6	0.60	0.43
33	D	TH3D336(1)016(3)0600	5.3	6	0.60	0.50
47	С	TH3C476(1)016(3)0800	7.5	6	0.80	0.37
47	С	TH3C476(1)016(3)0600	7.5	6	0.60	0.43
47	D	TH3D476(1)016(3)0600	7.5	6	0.60	0.43
68	D	TH3D686(1)016(3)0600	10.9	6	0.60	0.50
100	D	TH3D107(1)016(3)0600	16.0	8	0.60	0.50
100	E	TH3E107(1)016(3)0600	16.0	8	0.60	0.56
100	E	TH3E107(1)016(3)0150	16.0	8	0.15	1.11

- Part number definitions:
 - (1) Capacitance tolerance: K, M
 - (2) Termination and packaging: C, D, E, F, V, U, T, W
 (3) Termination and packaging: A, B, C, D, E, F, V, U, T, W



CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μA)	MAX. DF AT +25 °C (%)	MAX. ESR AT +25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		20 V _{DC} AT +85 °C; 13 V _{DC}	AT +125 °C; 10 V _r	oc AT +150 °C	(/	(4
1.0	Α	TH3A105(1)020(3)5900	0.5	4	5.90	0.11
2.2	Α	TH3A225(1)020(3)5900	0.5	6	5.90	0.11
2.2	В	TH3B225(1)020(2)3500	0.5	6	3.50	0.16
3.3	В	TH3B335(1)020(2)2700	0.7	6	2.70	0.18
3.3	C	TH3C335(1)020(3)2700	0.7	6	2.70	0.20
4.7	A	TH3A475(1)020(3)5000	0.9	6	5.00	0.12
4.7	В	TH3B475(1)020(2)2900	0.9	6	2.90	0.17
4.7	В	TH3B475(1)020(2)1900	0.9	6	1.90	0.21
4.7	C	TH3C475(1)020(3)1700	0.9	6	1.70	0.25
10	C	TH3C106(1)020(3)1100	2.0	6	1.10	0.23
		() ()			2.00	
15	В	TH3B156(1)020(2)2000	3.0	6		0.21
15	С	TH3C156(1)020(3)1000	3.0	6	1.00	0.33
15	D	TH3D156(1)020(3)0900	3.0	6	0.90	0.41
22	C	TH3C226(1)020(3)1000	4.4	6	1.00	0.33
22	D	TH3D226(1)020(3)0700	4.4	6	0.70	0.46
33	D	TH3D336(1)020(3)0600	6.6	6	0.60	0.5
47	D	TH3D476(1)020(3)0700	9.4	6	0.70	0.46
47	E	TH3E476(1)020(3)0600	9.4	8	0.60	0.56
68	E	TH3E686(1)020(3)0600	13.6	8	0.60	0.56
		25 V _{DC} AT +85 °C; 17 V _{DC}		_{DC} AT +150 °C		
0.47	Α	TH3A474(1)025(3)14R0	0.5	4	14.00	0.073
1.0	Α	TH3A105(1)025(3)5200	0.5	4	5.20	0.12
1.0	Α	TH3A105(1)025(3)3000	0.5	4	3.00	0.16
1.0	В	TH3B105(1)025(2)5000	0.5	4	5.00	0.13
2.2	Α	TH3A225(1)025(3)5200	0.6	6	5.20	0.12
2.2	В	TH3B225(1)025(2)3000	0.6	6	3.00	0.17
3.3	В	TH3B335(1)025(2)3000	0.8	6	3.00	0.17
3.3	С	TH3C335(1)025(3)2000	0.8	6	2.00	0.23
4.7	Α	TH3A475(1)025(3)5000	1.2	6	5.00	0.12
4.7	В	TH3B475(1)025(2)2800	1.2	6	2.80	0.17
4.7	С	TH3C475(1)025(3)1600	1.2	6	1.60	0.26
6.8	В	TH3B685(1)025(2)2400	1.7	6	2.40	0.19
6.8	С	TH3C685(1)025(3)1400	1.7	6	1.40	0.28
10	С	TH3C106(1)025(3)1100	2.5	6	1.10	0.32
10	D	TH3D106(1)025(3)0900	2.5	6	0.90	0.41
15	В	TH3B156(1)025(2)2000	3.8	6	2.00	0.21
15	В	TH3B156(1)025(2)1400	3.8	6	1.40	0.25
15	С	TH3C156(1)025(3)1200	3.8	6	1.20	0.30
15	D	TH3D156(1)025(3)0700	3.8	6	0.70	0.46
22	D	TH3D226(1)025(3)0600	5.5	6	0.60	0.50
33	D	TH3D336(1)025(3)0500	8.3	6	0.50	0.55
47	E	TH3E476(1)025(3)0600	11.8	6	0.60	0.56

- Part number definitions:
 - (1) Capacitance tolerance: K, M

 - (2) Termination and packaging: C, D, E, F, V, U, T, W
 (3) Termination and packaging: A, B, C, D, E, F, V, U, T, W



STANDARD	RATINGS					
CAPACITANCE (μF)	CASE CODE	PART NUMBER	MAX. DCL AT +25 °C (μA)	MAX. DF AT +25 °C (%)	MAX. ESR AT +25 °C 100 kHz (Ω)	MAX. RIPPLE 100 kHz I _{RMS} (A)
		35 V _{DC} AT +85 °C; 23 V _{DC} A	AT +125 °C; 17.5 V	_{DC} AT +150 °C		
0.33	Α	TH3A334(1)035(3)11R0	0.5	4	11.00	0.08
1.0	Α	TH3A105(1)035(3)6600	0.5	4	6.60	0.11
1.0	В	TH3B105(1)035(2)4400	0.5	4	4.40	0.14
1.5	В	TH3B155(1)035(2)4200	0.5	6	4.20	0.14
1.5	С	TH3C155(1)035(3)3300	0.5	6	3.30	0.18
2.2	В	TH3B225(1)035(2)2500	0.8	6	2.50	0.18
2.2	С	TH3C225(1)035(3)2200	0.8	6	2.20	0.22
3.3	В	TH3B335(1)035(2)3500	1.2	6	3.50	0.16
3.3	В	TH3B335(1)035(2)2500	1.2	6	2.50	0.18
3.3	С	TH3C335(1)035(3)1700	1.2	6	1.70	0.25
4.7	В	TH3B475(1)035(2)3100	1.7	6	3.10	0.17
4.7	С	TH3C475(1)035(3)1300	1.6	6	1.30	0.29
4.7	D	TH3D475(1)035(3)1000	1.6	6	1.00	0.39
6.8	С	TH3C685(1)035(3)1800	2.4	6	1.80	0.25
6.8	D	TH3D685(1)035(3)0900	2.4	6	0.90	0.41
10	С	TH3C106(1)035(3)1600	3.5	6	1.60	0.26
10	D	TH3D106(1)035(3)0700	3.5	6	0.70	0.46
10	D	TH3D106(1)035(3)0300	3.5	6	0.30	0.71
10	D	TH3D106(1)035(3)0250	3.5	6	0.25	0.77
15	D	TH3D156(1)035(3)0700	5.3	6	0.70	0.46
22	D	TH3D226(1)035(3)0600	7.7	6	0.60	0.50
22	D	TH3D226(1)035(3)0300	7.7	6	0.30	0.71
22	E	TH3E226(1)035(3)0500	7.7	6	0.50	0.61
		50 V _{DC} AT +85 °C; 33 V _{DC}	AT +125 °C; 25 V _D	OC AT +150 °C		
1.0	С	TH3C105(1)050(3)3300	0.5	4	3.30	0.18
3.3	D	TH3D335(1)050(3)1700	1.7	6	1.70	0.30
4.7	С	TH3C475(1)050(3)1500	2.4	6	1.50	0.27
4.7	D	TH3D475(1)050(3)0900	2.4	6	0.90	0.41
6.8	D	TH3D685(1)050(3)0900	3.4	6	0.90	0.41
10	D	TH3D106(1)050(3)0800	5.0	6	0.80	0.43
10	E	TH3E106(1)050(3)0500	5.0	6	0.50	0.61

- Part number definitions:
- (1) Capacitance tolerance: K, M
- (2) Termination and packaging: C, D, E, F, V, U, T, W
 (3) Termination and packaging: A, B, C, D, E, F, V, U, T, W

POWER DISSIPATION	
CASE CODE	MAXIMUM PERMISSIBLE POWER DISSIPATION AT +25 °C (W) IN FREE AIR
A	0.075
В	0.085
С	0.110
D	0.150
E	0.165



STANDARD PACKAGING QUANTITY					
CASE CODE	UNITS P	PER REEL			
CASE CODE	7" REEL	13" REEL			
A	2000	9000			
В	2000	8000			
С	500	3000			
D	500	2500			
E	400	1500			

PRODUCT INFORMATION				
Guide for Molded Tantalum Capacitors				
Pad Dimensions	www.vishay.com/doc?40074			
Package Dimensions				
Moisture Sensitivity (MSL)	www.vishay.com/doc?40135			
SELECTOR GUIDES				
Solid Tantalum Selector Guide	www.vishay.com/doc?49053			
Solid Tantalum Chip Capacitors	www.vishay.com/doc?40091			
FAQ				
Frequently Asked Questions	www.vishay.com/doc?40110			



Guide for Molded Tantalum Capacitors

INTRODUCTION

Tantalum electrolytic capacitors are the preferred choice in applications where volumetric efficiency, stable electrical parameters, high reliability, and long service life are primary considerations. The stability and resistance to elevated temperatures of the tantalum / tantalum oxide / manganese dioxide system make solid tantalum capacitors an appropriate choice for today's surface-mount assembly technology.

Vishay Sprague has been a pioneer and leader in this field, producing a large variety of tantalum capacitor types for consumer, industrial, automotive, military, and aerospace electronic applications.

Tantalum is not found in its pure state. Rather, it is commonly found in a number of oxide minerals, often in combination with Columbium ore. This combination is known as "tantalite" when its contents are more than one-half tantalum. Important sources of tantalite include Australia, Brazil, Canada, China, and several African countries. Synthetic tantalite concentrates produced from tin slags in Thailand, Malaysia, and Brazil are also a significant raw material for tantalum production.

Electronic applications, and particularly capacitors, consume the largest share of world tantalum production. Other important applications for tantalum include cutting tools (tantalum carbide), high temperature super alloys, chemical processing equipment, medical implants, and military ordnance.

Vishay Sprague is a major user of tantalum materials in the form of powder and wire for capacitor elements and rod and sheet for high temperature vacuum processing.

THE BASICS OF TANTALUM CAPACITORS

Most metals form crystalline oxides which are non-protecting, such as rust on iron or black oxide on copper. A few metals form dense, stable, tightly adhering, electrically insulating oxides. These are the so-called "valve" metals and include titanium, zirconium, niobium, tantalum, hafnium, and aluminum. Only a few of these permit the accurate control of oxide thickness by electrochemical means. Of these, the most valuable for the electronics industry are aluminum and tantalum.

Capacitors are basic to all kinds of electrical equipment, from radios and television sets to missile controls and automobile ignitions. Their function is to store an electrical charge for later use.

Capacitors consist of two conducting surfaces, usually metal plates, whose function is to conduct electricity. They are separated by an insulating material or dielectric. The dielectric used in all tantalum electrolytic capacitors is tantalum pentoxide.

Tantalum pentoxide compound possesses high-dielectric strength and a high-dielectric constant. As capacitors are being manufactured, a film of tantalum pentoxide is applied to their electrodes by means of an electrolytic process. The film is applied in various thicknesses and at various voltages and although transparent to begin with, it takes on different colors as light refracts through it. This coloring occurs on the tantalum electrodes of all types of tantalum capacitors.

Rating for rating, tantalum capacitors tend to have as much as three times better capacitance / volume efficiency than aluminum electrolytic capacitors. An approximation of the capacitance / volume efficiency of other types of capacitors may be inferred from the following table, which shows the dielectric constant ranges of the various materials used in each type. Note that tantalum pentoxide has a dielectric constant of 26, some three times greater than that of aluminum oxide. This, in addition to the fact that extremely thin films can be deposited during the electrolytic process mentioned earlier, makes the tantalum capacitor extremely efficient with respect to the number of microfarads available per unit volume. The capacitance of any capacitor is determined by the surface area of the two conducting plates, the distance between the plates, and the dielectric constant of the insulating material between the plates.

COMPARISON OF CAPACITOR DIELECTRIC CONSTANTS				
DIELECTRIC	e DIELECTRIC CONSTANT			
Air or vacuum	1.0			
Paper	2.0 to 6.0			
Plastic	2.1 to 6.0			
Mineral oil	2.2 to 2.3			
Silicone oil	2.7 to 2.8			
Quartz	3.8 to 4.4			
Glass	4.8 to 8.0			
Porcelain	5.1 to 5.9			
Mica	5.4 to 8.7			
Aluminum oxide	8.4			
Tantalum pentoxide	26			
Ceramic	12 to 400K			

In the tantalum electrolytic capacitor, the distance between the plates is very small since it is only the thickness of the tantalum pentoxide film. As the dielectric constant of the tantalum pentoxide is high, the capacitance of a tantalum capacitor is high if the area of the plates is large:

$$C = \frac{eA}{t}$$

where

C = capacitance

e = dielectric constant

A = surface area of the dielectric

t = thickness of the dielectric

Tantalum capacitors contain either liquid or solid electrolytes. In solid electrolyte capacitors, a dry material (manganese dioxide) forms the cathode plate. A tantalum lead is embedded in or welded to the pellet, which is in turn connected to a termination or lead wire. The drawings show the construction details of the surface-mount types of tantalum capacitors shown in this catalog.



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SOLID ELECTROLYTE TANTALUM CAPACITORS

Solid electrolyte capacitors contain manganese dioxide, which is formed on the tantalum pentoxide dielectric layer by impregnating the pellet with a solution of manganous nitrate. The pellet is then heated in an oven, and the manganous nitrate is converted to manganese dioxide.

The pellet is next coated with graphite, followed by a layer of metallic silver, which provides a conductive surface between the pellet and the leadframe.

Molded Chip tantalum capacitor encases the element in plastic resins, such as epoxy materials. The molding compound has been selected to meet the requirements of UL 94 V-0 and outgassing requirements of ASTM E-595. After assembly, the capacitors are tested and inspected to assure long life and reliability. It offers excellent reliability and high stability for consumer and commercial electronics with the added feature of low cost

Surface-mount designs of "solid tantalum" capacitors use lead frames or lead frameless designs as shown in the accompanying drawings.

TANTALUM CAPACITORS FOR ALL DESIGN CONSIDERATIONS

Solid electrolyte designs are the least expensive for a given rating and are used in many applications where their very small size for a given unit of capacitance is of importance. They will typically withstand up to about 10 % of the rated DC working voltage in a reverse direction. Also important are their good low temperature performance characteristics and freedom from corrosive electrolytes.

Vishay Sprague patented the original solid electrolyte capacitors and was the first to market them in 1956. Vishay Sprague has the broadest line of tantalum capacitors and has continued its position of leadership in this field. Data sheets covering the various types and styles of Vishay Sprague capacitors for consumer and entertainment electronics, industry, and military applications are available where detailed performance characteristics must be specified.





COMMERCIAL PRODUCTS

SOLID TANTA	SOLID TANTALUM CAPACITORS - MOLDED CASE						
SERIES	293D	793DX-CTC3- CTC4	593D	TR3	TP3	TL3	
PRODUCT IMAGE	In the last last last	In the line lines	***************************************		150 FE	180 0 00 X 18 18 18 18 18 18 18 18 18 18 18 18 18	
TYPE		Surface-m	ount Tantamount™, i	molded case			
FEATURES	Standard industrial grade	CECC approved	Low ESR	Low ESR	High performance, automotive grade	Very low DCL	
TEMPERATURE RANGE			-55 °C to -	+125 °C			
CAPACITANCE RANGE	0.1 μF to 1000 μF	0.1 μF to 100 μF	1 μF to 470 μF	0.47 μF to 1000 μF	0.1 μF to 470 μF	0.1 μF to 470 μF	
VOLTAGE RANGE	4 V to 75 V	4 V to 50 V	4 V to 50 V	4 V to 75 V	4 V to 50 V	4 V to 50 V	
CAPACITANCE TOLERANCE			± 10 %, ±	± 20 %			
LEAKAGE CURRENT	0.01 CV or 0.5 μA, whichever is greater					0.005 CV or 0.25 µA, whichever is greater	
DISSIPATION FACTOR	4 % to 30 %	4 % to 6 %	4 % to 15 %	4 % to 30 %	4 % to 15 %	4 % to 15 %	
CASE CODES	A, B, C, D, E	A, B, C, D	A, B, C, D, E	A, B, C, D, E, W	A, B, C, D, E	A, B, C, D, E	
TERMINATION		10	00 % matte tin standa	rd, tin / lead available			

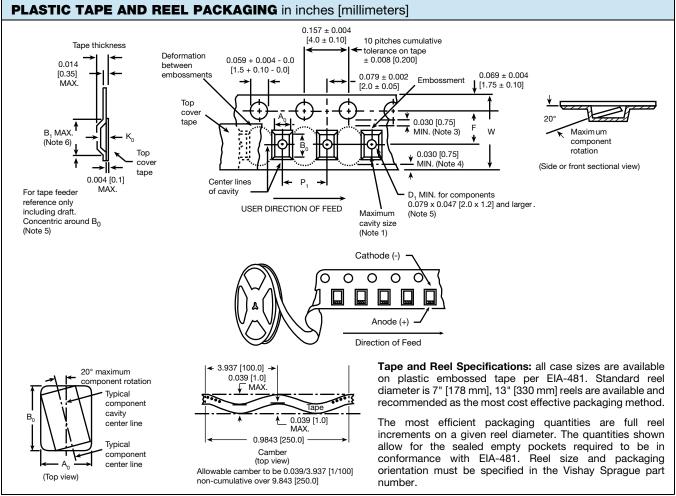
SOLID TANTA	SOLID TANTALUM CAPACITORS - MOLDED CASE						
SERIES	TX3	TH3	TH4	TH5			
PRODUCT IMAGE	33.X20 R2 R2	15285 15285	The state of the s	Bus &			
TYPE		Surface-mount TANTAI	MOUNT™, molded case				
FEATURES	E-detonators	High temperature +150 °C, automotive grade	High temperature +175 °C, automotive grade	Very high temperature +200 °C			
TEMPERATURE RANGE	-55 °C to +125 °C	-55 °C to +150 °C	-55 °C to +175 °C	-55 °C to +200 °C			
CAPACITANCE RANGE	10 μF to 100 μF	0.33 μF to 220 μF	10 μF to 100 μF	4.7 μF to 100 μF			
VOLTAGE RANGE	16 V to 25 V	6.3 V to 50 V	6.3 V to 35 V	5 V to 24 V			
CAPACITANCE TOLERANCE		± 10 %,	± 20 %				
LEAKAGE CURRENT	0.005 CV	0.01	CV or 0.5 μA, whichever is gre	eater			
DISSIPATION FACTOR	6 % to 20 %	4 % to 8 %	4.5 % to 8 %	6 % to 10 %			
CASE CODES	B, C	A, B, C, D, E	B, C, D, E	D, E			
TERMINATION	100 % matte tin	100 % matte tin standard, tin / lead and gold plated available	100 % matte tin	Gold plated			



HIGH RELIABILITY PRODUCTS

SOLID TANTALUM CAPACITORS - MOLDED CASE						
SERIES	тмз	T83	CWR11	95158		
PRODUCT IMAGE	Lines Rungo	47116 70 (2)		00 00 00 00 00 00 00 00 00 00 00 00 00		
ТҮРЕ	TANTAMOUNT™, molded case, hi-rel.	TANTAMOUNT™, molded case, hi-rel. COTS	TANTAMOUNT™, molded case, DLA approved			
FEATURES	High reliability, for medical Instruments	High reliability, standard and low ESR	MIL-PRF-55365/8 qualified	Low ESR		
TEMPERATURE RANGE		-55 °C to	+125 °C			
CAPACITANCE RANGE	1 μF to 220 μF	0.1 μF to 470 μF	0.1 μF to 100 μF	4.7 μF to 220 μF		
VOLTAGE RANGE	4 V to 20 V	4 V to 63 V	4 V to	50 V		
CAPACITANCE TOLERANCE	± 10 %, ± 2	20 %	± 5 %, ± 10 %, ± 20 %	± 10 %, ± 20 %		
LEAKAGE CURRENT	$0.005~\text{CV}$ or $0.25~\mu\text{A},$ whichever is greater	0.0	1 CV or 0.5 μA, whichever is g	greater		
DISSIPATION FACTOR	4 % to 8 %	4 % to 15 % 4 % to 6 % 4 % to 12		4 % to 12 %		
CASE CODES	A, B, C, D, E	A, B, C, D, E	A, B, C, D	C, D, E		
TERMINATION	100 % matte tin; tin / lead	100 % matte tin; tin / lead; tin / lead solder fused	Tin / lead; tin / lead solder fused	Tin / lead solder plated; gold plated		

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Notes

- Metric dimensions will govern. Dimensions in inches are rounded and for reference only
- (1) A₀, B₀, K₀, are determined by the maximum dimensions to the ends of the terminals extending from the component body and / or the body dimensions of the component. The clearance between the ends of the terminals or body of the component to the sides and depth of the cavity (A₀, B₀, K₀) must be within 0.002" (0.05 mm) minimum and 0.020" (0.50 mm) maximum. The clearance allowed must also prevent rotation of the component within the cavity of not more than 20°
- (2) Tape with components shall pass around radius "R" without damage. The minimum trailer length may require additional length to provide "R" minimum for 12 mm embossed tape for reels with hub diameters approaching N minimum
- (3) This dimension is the flat area from the edge of the sprocket hole to either outward deformation of the carrier tape between the embossed cavities or to the edge of the cavity whichever is less
- (4) This dimension is the flat area from the edge of the carrier tape opposite the sprocket holes to either the outward deformation of the carrier tape between the embossed cavity or to the edge of the cavity whichever is less
- (5) The embossed hole location shall be measured from the sprocket hole controlling the location of the embossment. Dimensions of embossment location shall be applied independent of each other
- (6) B₁ dimension is a reference dimension tape feeder clearance only

CASE CODE	TAPE SIZE	B ₁ (MAX.)	D ₁ (MIN.)	F	K ₀ (MAX.)	P ₁	w
MOLDED	MOLDED CHIP CAPACITORS; ALL TYPES						
Α	8 mm	0.165	0.039	0.138 ± 0.002	0.094	0.157 ± 0.004	0.315 ± 0.012
В	0 111111	[4.2]	[1.0]	$[3.5 \pm 0.05]$	[2.4]	$[4.0 \pm 1.0]$	$[8.0 \pm 0.30]$
С							
D	12 mm	0.32	0.059	0.217 ± 0.00	0.177	0.315 ± 0.004	0.472 ± 0.012
Е	12 111111	[8.2]	[1.5]	$[5.5 \pm 0.05]$	[4.5]	$[8.0 \pm 1.0]$	$[12.0 \pm 0.30]$
W							



RECOMMENDED REFLOW PROFILES Capacitors should withstand reflow profile as per J-STD-020 standard, three cycles. T_C - 5 °C Max. ramp-up rate = 3 °C/s Max. ramp-down rate = 6 °C/s (°C) Preheat area T_{s min.} 25 Time 25 °C to peak TIME (s) **PROFILE FEATURE** SnPb EUTECTIC ASSEMBLY **LEAD (Pb)-FREE ASSEMBLY** Preheat / soak Temperature min. (T_{s min.}) 100 °C 150 °C Temperature max. (T_{s max.}) 150 °C 200 °C Time (t_s) from $(T_{s min.} to T_{s max.})$ 60 s to 120 s 60 s to 120 s Ramp-up Ramp-up rate (T_L to T_D) 3 °C/s max. 3 °C/s max. 217 °C 183 °C Liquidus temperature (T_L) Time (t₁) maintained above T₁ 60 s to 150 s 60 s to 150 s Peak package body temperature (Tp) Depends on case size - see table below Time (t_p) within 5 °C of the specified classification temperature (T_C) 20 s 30 s Time 25 °C to peak temperature 6 min max. 8 min max. Ramp-down Ramp-down rate (Tp to TL) 6 °C/s max. 6 °C/s max.

PEAK PACKAGE BODY TEMPERATURE (Tp)				
CASE CODE	PEAK PACKAGE BODY TEMPERATURE (Tp)			
CASE CODE	SnPb EUTECTIC PROCESS	LEAD (Pb)-FREE PROCESS		
A, B, C	235 °C	260 °C		
D, E, W	220 °C	250 °C		



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GUIDE TO APPLICATION

 AC Ripple Current: the maximum allowable ripple current shall be determined from the formula:

$$I_{RMS} = \sqrt{\frac{P}{R_{ESR}}}$$

where,

P = power dissipation in W at +25 °C as given in the tables in the product datasheets (Power Dissipation).

R_{ESR} = the capacitor equivalent series resistance at the specified frequency

2. **AC Ripple Voltage:** the maximum allowable ripple voltage shall be determined from the formula:

$$V_{RMS} = I_{RMS} \times Z$$

or, from the formula:

$$V_{RMS} = Z \sqrt{\frac{P}{R_{ESR}}}$$

where.

P = power dissipation in W at +25 °C as given in the tables in the product datasheets (Power Dissipation).

R_{ESR} = the capacitor equivalent series resistance at the specified frequency

Z = the capacitor impedance at the specified frequency

- 2.1 The sum of the peak AC voltage plus the applied DC voltage shall not exceed the DC voltage rating of the capacitor.
- 2.2 The sum of the negative peak AC voltage plus the applied DC voltage shall not allow a voltage reversal exceeding 10 % of the DC working voltage at \$25 °C\$
- Reverse Voltage: solid tantalum capacitors are not intended for use with reverse voltage applied. However, they have been shown to be capable of withstanding momentary reverse voltage peaks of up to 10 % of the DC rating at 25 °C and 5 % of the DC rating at +85 °C.
- 4. Temperature Derating: if these capacitors are to be operated at temperatures above +25 °C, the permissible RMS ripple current shall be calculated using the derating factors as shown:

TEMPERATURE (°C)	DERATING FACTOR
+25	1.0
+85	0.9
+125	0.4
+150 ⁽¹⁾	0.3
+175 ⁽¹⁾	0.2
+200 ⁽¹⁾	0.1

Note

(1) Applicable for dedicated high temperature product series

5. Power Dissipation: power dissipation will be affected by the heat sinking capability of the mounting surface. Non-sinusoidal ripple current may produce heating effects which differ from those shown. It is important that the equivalent I_{BMS} value be established when calculating permissible operating levels. (Power dissipation calculated using +25 °C temperature rise).

6. **Printed Circuit Board Materials:** molded capacitors are compatible with commonly used printed circuit board materials (alumina substrates, FR4, FR5, G10, PTFE-fluorocarbon and porcelanized steel).

7. Attachment:

- 7.1 **Solder Paste:** the recommended thickness of the solder paste after application is 0.007" ± 0.001" [0.178 mm ± 0.025 mm]. Care should be exercised in selecting the solder paste. The metal purity should be as high as practical. The flux (in the paste) must be active enough to remove the oxides formed on the metallization prior to the exposure to soldering heat. In practice this can be aided by extending the solder preheat time at temperatures below the liquidous state of the solder.
- 7.2 **Soldering:** capacitors can be attached by conventional soldering techniques; vapor phase, convection reflow, infrared reflow, wave soldering, and hot plate methods. The soldering profile charts show recommended time / temperature conditions for soldering. Preheating is recommended. The recommended maximum ramp rate is 3 °C per second. Attachment with a soldering iron is not recommended due to the difficulty of controlling temperature and time at temperature. The soldering iron must never come in contact with the capacitor. For details see www.vishay.com/doc?40214.
- 7.2.1 Backward and Forward Compatibility: capacitors with SnPb or 100 % tin termination finishes can be soldered using SnPb or lead (Pb)-free soldering processes.
- 8. Cleaning (Flux Removal) After Soldering: molded capacitors are compatible with all commonly used solvents such as TES, TMS, Prelete, Chlorethane, Terpene and aqueous cleaning media. However, CFC / ODS products are not used in the production of these devices and are not recommended. Solvents containing methylene chloride or other epoxy solvents should be avoided since these will attack the epoxy encapsulation material.
- 8.1 When using ultrasonic cleaning, the board may resonate if the output power is too high. This vibration can cause cracking or a decrease in the adherence of the termination. DO NOT EXCEED 9W/I at 40 kHz for 2 min.
- 9. Recommended Mounting Pad Geometries: proper mounting pad geometries are essential for successful solder connections. These dimensions are highly process sensitive and should be designed to minimize component rework due to unacceptable solder joints. The dimensional configurations shown are the recommended pad geometries for both wave and reflow soldering techniques. These dimensions are intended to be a starting point for circuit board designers and may be fine tuned if necessary based upon the peculiarities of the soldering process and / or circuit board design.



Molded Chip Tantalum Capacitors, Automotive Grade

ELECTRICAL PERFO	RMANCE CHAR	ACTERISTICS				
ITEM	PERFORMANCE C	PERFORMANCE CHARACTERISTICS				
Category temperature range	-55 °C to +85 °C (to +125 °C / +150 °C / +175 °C with voltage derating - refer to graph "Category Voltage vs. Temperature") (1)					
Capacitance tolerance	± 20 %, ± 10 %, tested via bridge method, at 25 °C, 120 Hz					
Dissipation factor	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 120 Hz					
ESR	Limits per Standard Ratings table. Tested via bridge method, at 25 °C, 100 kHz					
Leakage current	After application of rated voltage applied to capacitors for 5 min using a steady source of power with 1 k Ω resistor in series with the capacitor under test, leakage current at 25 °C is not more than 0.01 CV or 0.5 μ A, whichever is greater. Note that the leakage current varies with temperature and applied voltage. See graph "Typical Leakage Current Temperature Factor" for the appropriate adjustment factor.					
Capacitance change by temperature	+30 % max. (at +175 °C) +20 % max. (at +125 °C and +150 °C) +10 % max. (at +85 °C) -10 % max. (at -55 °C)					
Reverse voltage	Capacitors are capable of withstanding peak voltages in the reverse direction equal to: 10 % of the DC rating at +25 °C 5 % of the DC rating at +85 °C 1 % of the DC rating at +125 °C					
Ripple current	For maximum ripple current values (at 25 °C) refer to relevant datasheet. If capacitors are to be used at temperatures above +25 °C, the permissible RMS ripple current (or voltage) shall be calculated using the derating factors: 1.0 at +25 °C 0.9 at +85 °C 0.4 at +125 °C 0.3 at +150 °C 0.2 at +175 °C					
Maximum operating	+85	5 °C	+12	+150 °C / +175 °C		
and surge voltages vs. temperature	RATED VOLTAGE (V)	SURGE VOLTAGE (V)	CATEGORY VOLTAGE (V)	SURGE VOLTAGE (V)	CATEGORY VOLTAGE (V)	
	4	5.2	2.7	3.4	n/a	
	6.3	8	4	5	3	
	10	13	7	8	5	
	16	20	10	12	8	
	20	26	13	16	10	
	25	32	17	20	12.5	
	35	46	23	28	17.5	
	50	65	33	40	25	
	50 ⁽²⁾	60	33	40	n/a	
	63	75	42	50	n/a	
	75 ⁽³⁾	75	50	50	n/a	

- All information presented in this document reflects typical performance characteristics
- (1) Series TH3 up to 150 °C; TH4 up to 175 °C (2) Capacitance value 15 μF and higher

(3) For 293D and TR3 only

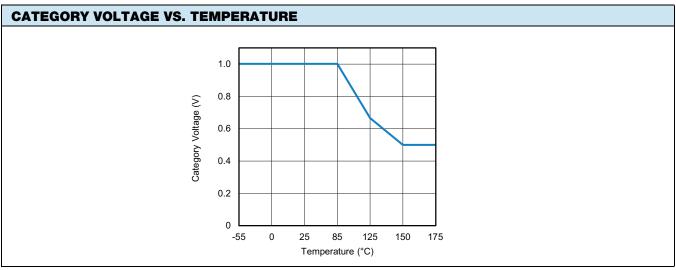


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RECOMMENDED VOLTAGE DERATING GUIDELINES (for temperature below +85 °C)			
VOLTAGE RAIL (V)	CAPACITOR VOLTAGE RATING (V)		
≤ 3.3	6.3		
5	10		
10	20		
12	25		
15	35		
24	50 or series configuration		

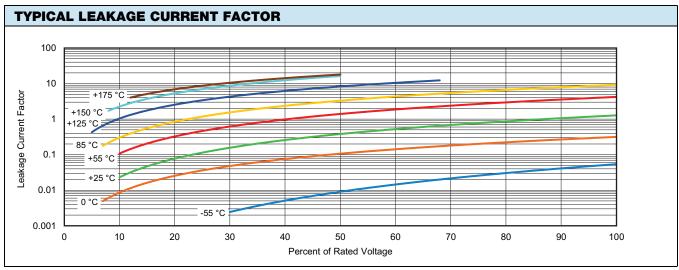
Notes

- For temperatures above +85 °C the same voltage derating ratio is recommended, but with respect to category voltage.
 Up to +85 °C: category voltage = rated voltage
 - At +125 °C: category voltage = 2/3 of rated voltage
- At 150 °C / 175 °C: category voltage = 1/2 of rated voltage
- For more information about recommended voltage derating see: www.vishay.com/doc?40246



Note

• Below 85 °C category voltage is equal to rated voltage



- At +25 °C, the leakage current shall not exceed the value listed in the Standard Ratings table.
 - At +85 °C, the leakage current shall not exceed 10 times the value listed in the Standard Ratings table.
 - At +125 °C, the leakage current shall not exceed 12 times the value listed in the Standard Ratings table.
 - At +150 °C, the leakage current shall not exceed 15 times the value listed in the Standard Ratings table.
 - At +175 °C, the leakage current shall not exceed 18 times the value listed in the Standard Ratings table

Typical Performance Characteristics

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ENVIRONMENTAL PERFORMANCE CHARACTERISTICS				
ITEM	CONDITION	POST TEST PERFORMANCE		
High temperature exposure (storage)	MIL-STD-202, method 108 1000 h, at maximum rated temperature, unpowered	Capacitance change Dissipation factor Leakage current ESR	Within ± 20 % of initial value Initial specified limit Initial specified limit Initial specified limit	
Operational life test at +125 °C	AEC-Q200 1000 h application 2/3 of rated voltage	Capacitance change Dissipation factor Leakage current ESR	Within ± 20 % of initial value Initial specified limit Shall not exceed 10 times the initial limit Initial specified limit	
Operational life test at +150 °C (for TH3) and at +175 °C (for TH4)	AEC-Q200 1000 h application 1/2 of rated voltage	Capacitance change Dissipation factor Leakage current ESR	Within ± 20 % of initial value Shall not exceed 3 times the initial limit Shall not exceed 10 times the initial limit Shall not exceed 3 times the initial limit	
Surge voltage	MIL-PRF-55365: 1000 successive test cycles at 85 °C of surge voltage (as specified in the table above), in series with a 33 Ω resistor at the rate of 30 s ON, 30 s OFF	Capacitance change Dissipation factor Leakage current ESR	Within ± 30 % of initial value Shall not exceed 1.5 times the initial limit Shall not exceed 2 times the initial limit Shall not exceed 1.5 times the initial limit	
Biased humidity test	AEC-Q200 At 85 °C / 85 % RH, 1000 h, with rated voltage applied	Capacitance change Dissipation factor Leakage current ESR	Within ± 20 % of initial value Shall not exceed 3 times the initial limit Shall not exceed 10 times the initial limit Shall not exceed 3 times the initial limit	
Temperature cycling	AEC-Q200 / JESD22, method JA-104 -55 °C / +125 °C, for 1000 cycles	Capacitance change Dissipation factor Leakage current ESR	Within ± 20 % of initial value Initial specified limit Initial specified limit Initial specified limit	

ITEM	CONDITION	POST TEST PERFORMANCE		
Vibration	MIL-STD-202, method 204: 10 Hz to 2000 Hz, 5 g peak for 20 min, 12 cycles each of 3 orientations (total 36 cycles), at rated voltage	Capacitance change Dissipation factor Leakage current	Within ± 20 % of initial value Initial specified limit Initial specified limit	
		There shall be no mechanical or visual damage to capacitors post-conditioning.		
Mechanical shock	MIL-STD-202, method 213, condition F, 1500 <i>g</i> peak, 0.5 ms, half-sine	Capacitance change Dissipation factor Leakage current	Within ± 20 % of initial value Initial specified limit Initial specified limit	
		There shall be no mechanical or visual damage to capacitors post-conditioning.		
Resistance to solder heat	MIL-STD-202, method 210, condition D Solder dip 260 °C ± 5 °C, 10 s	Capacitance change Dissipation factor Leakage current	Within ± 20 % of initial value Initial specified limit Initial specified limit	
Resistance to solvents	MIL-STD-202, method 215	Capacitance change Dissipation factor Leakage current	Within ± 20 % of initial value Initial specified limit Initial specified limit	
		There shall be no mech capacitors post-conditions Body marking shall rem	3	
Solderability	AEC-Q200 / J-STD-002	Electrical test not required		
Terminal strength / Shear force test	AEC-Q200-006 Apply a pressure load of 17.7 N (1.8 kg) for 60 s horizontally to the center of capacitor side body Exception: for case size 0603 pressure load is 5N	Part should not be sheared off the pads and no body cracking post-conditioning. Electrical test not required.		
Flammability	Encapsulation materials meet UL 94 V-0 with an oxygen index of 32 %	n/a		



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